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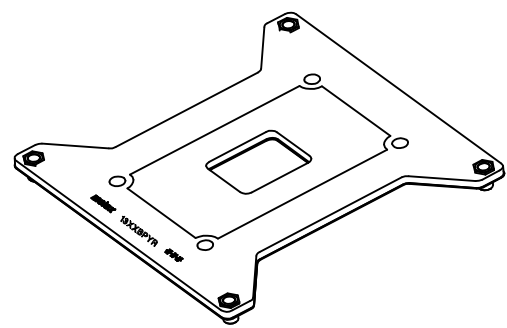
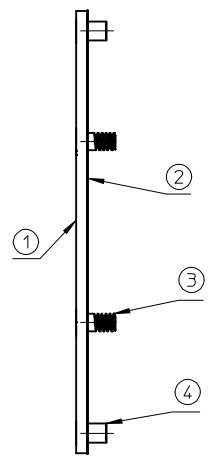
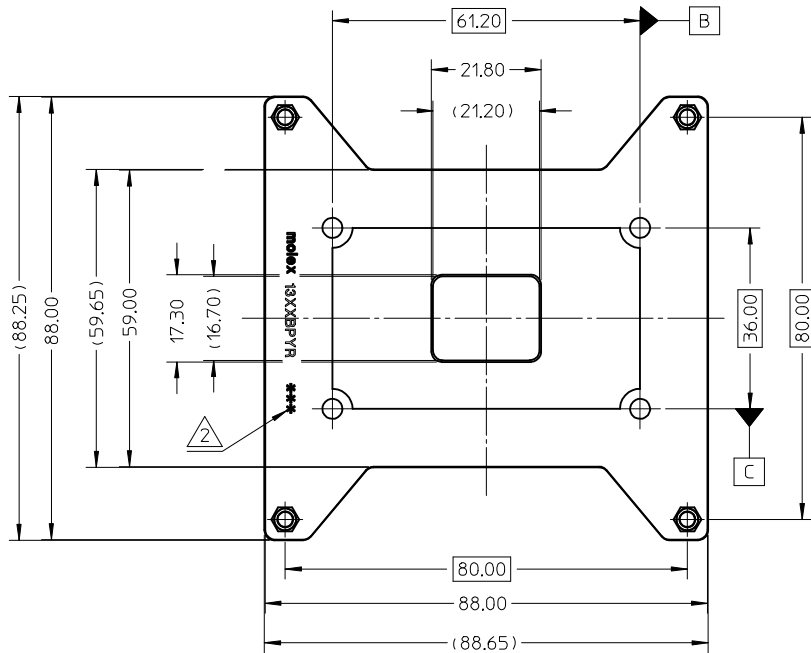
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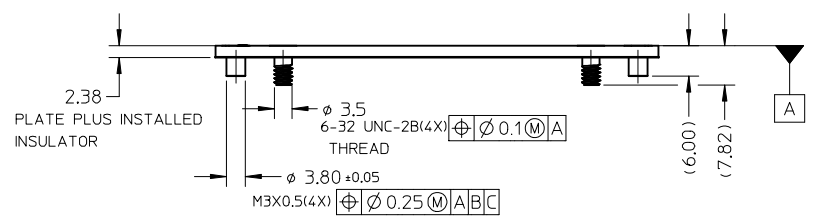
C

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- NOTES:
- MATE WITH LGA13XX ILM ASSEMBLY
DETAIL REFER TO SD-47593-900
 - DATE CODE
 - THE PARTS 475937000 COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV 2000/53/EC



BILL OF MATERIAL			
ITEM NO	QTY	DESCRIPTION	MATERIAL
	1	BACK PLATE ASSEMBLY FOR SERVER	
①	1	BACK PLATE	STEEL WITH NICKEL PLATING
②	1	BACK PLATE INSULATOR	FORMEX GK-5BK
③	4	BACK PLATE SCREW	STEEL WITH NICKEL PLATING
④	4	BACK PLATE NUT	STEEL

ENTER DESCRIPTION EC NO: SH2013-0064 DRWN: YXZHENG 2012/10/11 CHKD: APPR: AYIN 2013/02/06	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES	± ---	± ---	DRAWN BY YOSUN	DATE 2008/10/13	TITLE 13XX CKT SOCKET BACK PLATE ASSEMBLY FOR SERVER APPLICATION MOLEX INCORPORATED DOCUMENT NO. SD-47593-700 SHEET NO. 1 OF 1		
		3 PLACES	± ---	± ---	CHECKED BY JKACHLIC	DATE 2008/10/13			
		2 PLACES	± 0.2	± ---	APPROVED BY AYIN	DATE 2010/10/22			
1 PLACE	± 0.3	± ---	MATERIAL NO. 47593-7000						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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NOTES:

1. MATERIAL:

HOUSING: LCP,UL94V-0,COLOR:BLACK.
 TERMINAL:COPPER ALLOY.
 PICK AND PLACE COVER:LCP.
 SOLDER BALL:SEE THE TABLE.

2. PLATING:

SEE TABLE FOR GOLD ON CONTACT AREA.
 1.27 MICROMETER NICKEL UNDERPLATE.

3. DATE-CODE LOCATION, AND DATE-CODE "YMDLS"
 IS DEFINED AS:YEAR/MONTH/DAY/LS(LS IS MOLEX INTERNAL CONTROLLED)

4. PRODUCT NAME TO BE INDICATED IN THIS AREA.

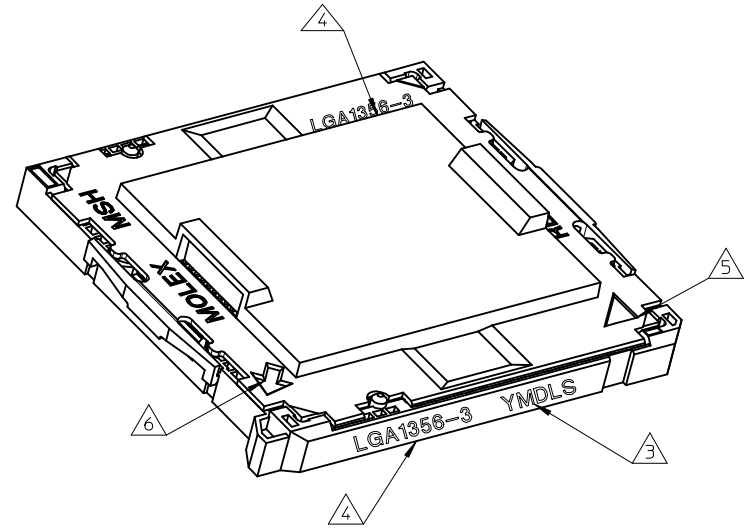
5. SOCKET PIN 1 INDICATOR.

6. ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.

7. PRODUCT SPECIFICATION PS-47594-001 APPLIES.

8. PRODUCT PACKAGE PK-47594-003 APPLIES.

9. THE PARTS 47594*001/*002 COMPLIANT TO RoHS
 DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.

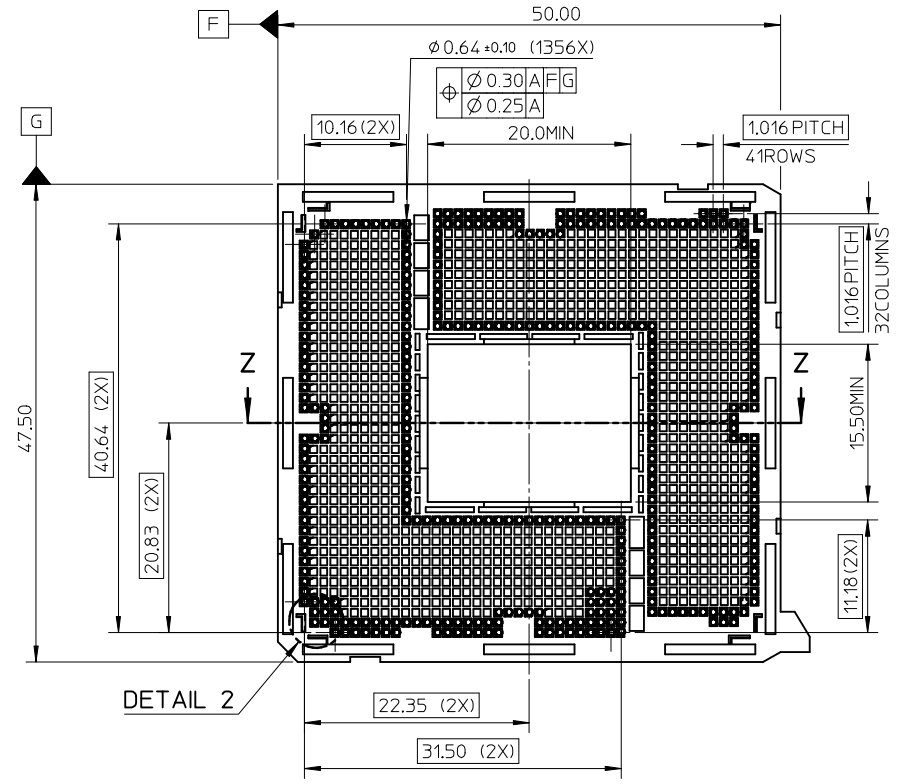
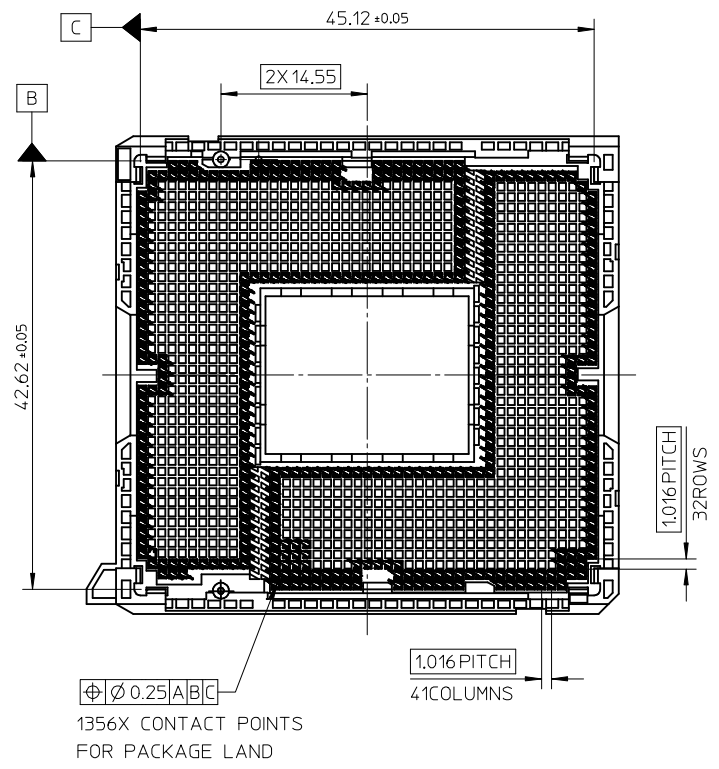


LGA1356 SOCKET PART NUMBER LIST					PART NAME
P/N	CUSTOMER	TERMINAL PLATING	SOLDER BALL	RoHS COMPLIANT	
475942001	GENERAL	15u*(0.38um)	LEAD FREE	YES	LGA1356-3(B3)
475942002	GENERAL	30u*(0.76um)			

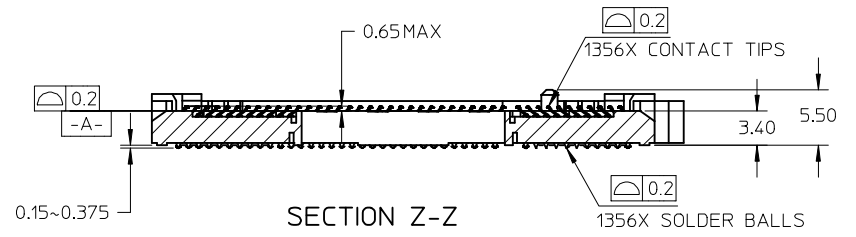
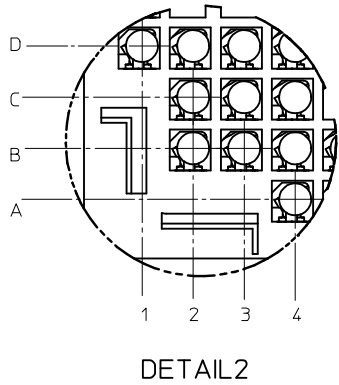
NEW RELEASED EC NO: SH2013-0064 DRWN: YXZHENG 2012/09/24 CH'KD: APPR: AYIN 2013/02/04 REV 1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla_F=0$	4 PLACES	mm	MM ONLY	2:1	METRIC	LGA1356-3 SOCKET(B3) FULL ASSEMBLY
	$\nabla_F=0$	3 PLACES	INCH	DRAWN BY	DATE	TITLE	
	$\nabla_F=0$	2 PLACES	± 0.20	$\pm \dots$	YXZHENG	2012/09/24	SD-47594-200
		1 PLACE	± 0.25	$\pm \dots$	CHECKED BY	DATE	
	0 PLACE	$\pm \dots$	$\pm \dots$	APPROVED BY	DATE	SD-47594-200	
	ANGULAR $\pm 1^\circ$		AYIN		2013/02/04		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		MATERIAL NO.	DOCUMENT NO.	SHEET NO.
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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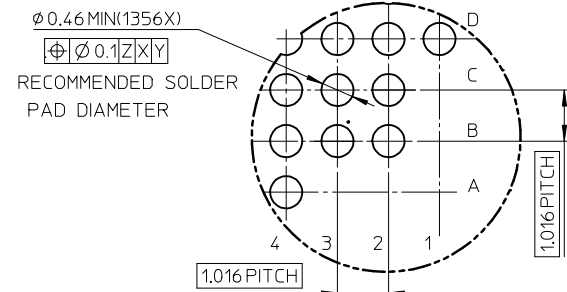
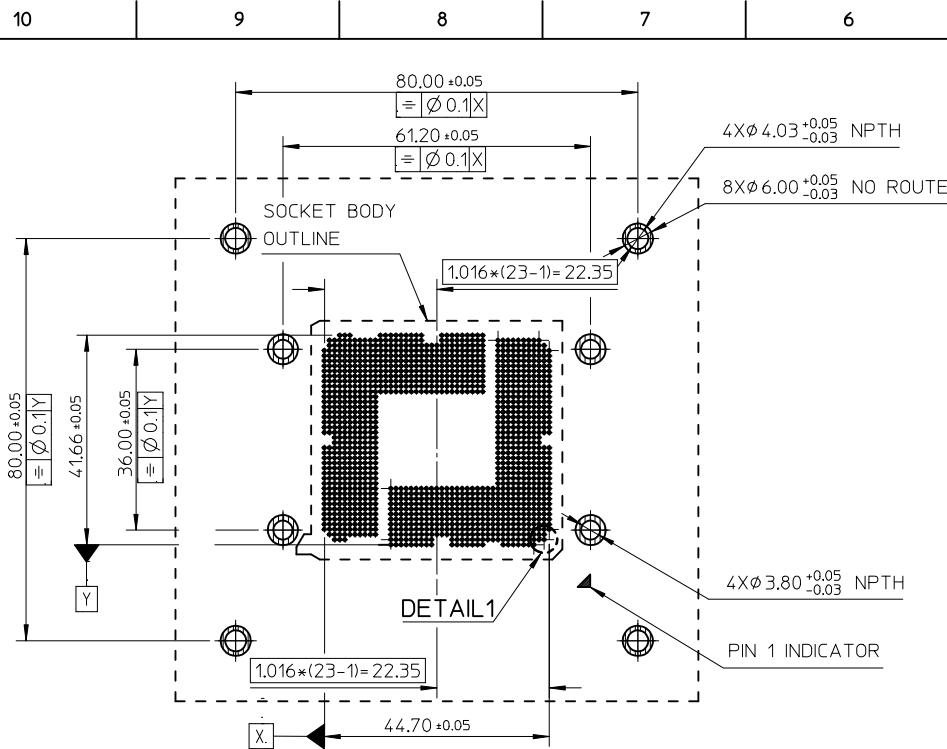


DETAIL 2

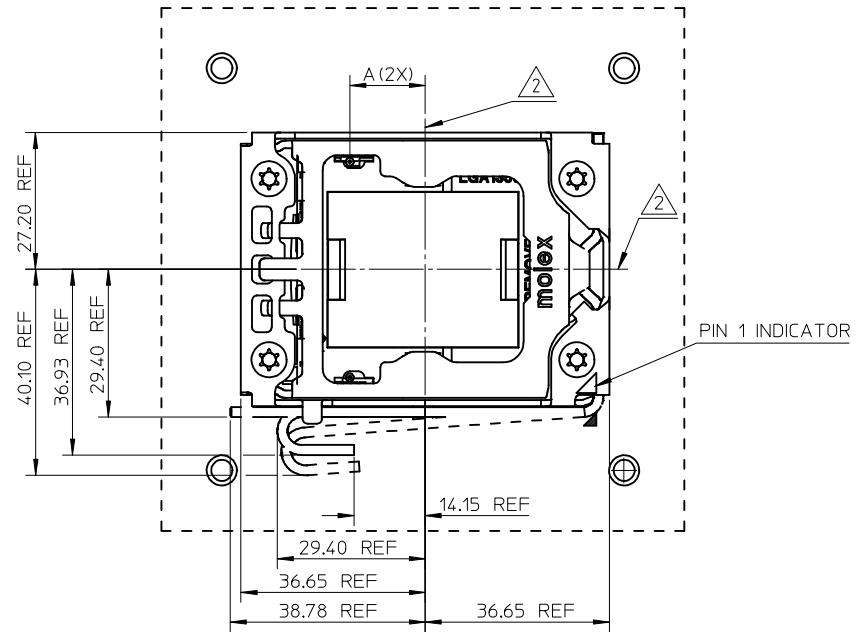


NEW RELEASED EC NO: SHZ013-0064 DRWN: YXZHENG 2012/09/24 CHKD: APPR: AYIN 2013/02/04	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.20 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY		
		ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY AYIN	DATE 2013/02/04	MATERIAL NO. SEE PAGE 1		DOCUMENT NO. SD-47594-200	SHEET NO. 2 OF 3
	1	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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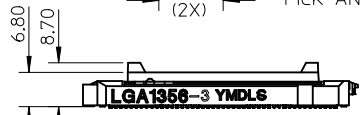
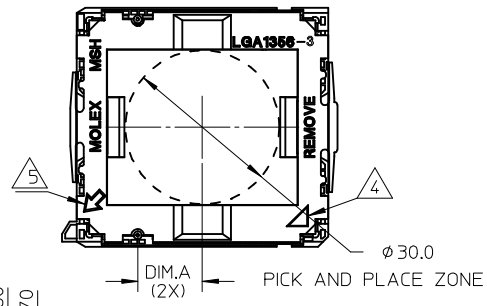


DETAIL1
SCALE 10:1



SOCKET ON PCB(FOR REFERENCE ONLY)
LOAD PLATE IS NOT LOCKED

RECOMMEND PCB LAYOUT
THICKNESS ARE 1.57+/-0.10 OR 2.54+/-0.10



- NOTES
- DATUM A IS THE PLANE WHICH SOCKET WILL BE SEATED.
 - GEOMETRIC CENTER OF CPU PACKAGE/SOCKET HOUSING CAVITY.
 - BOARD COMPONENT KEEP-INS AND MECHANICAL KEEP-OUTS TO BE UTILIZED WITH SUFFICIENT ALLOWANCES FOR PLACEMENT AND SIZE TOLERANCES ASSEMBLY PROCESS ACCESS, AND DYNAMIC EXCURSIONS.
 - SOCKET PIN 1 INDICATOR.
 - ARROW INDICATE THE ALIGN KEY FOR ILM ASSEMBLY.
 - ASSUME SYMMETRY FOR UNDIMENSIONED CORNERS AND EDGES.

NEW RELEASED IEC NO: SH2013-0064 DRWN: YXZHENG CHKD: APPR: AYIN 2012/09/24 2013/02/04	QUALITY SYMBOLS $F_{\Delta} = 0$ $F_{\square} = 0$ $F_{\nabla} = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY YXZHENG	DATE 2012/09/24	TITLE LGA1356-3 SOCKET(B3) FULL ASSEMBLY					
		3 PLACES ± --- ± ---		CHECKED BY DATE		MATERIAL NO. SEE PAGE 1					
		2 PLACES ± 0.20 ± ---		APPROVED BY AYIN		DATE 2013/02/04	DOCUMENT NO. SD-47594-200				
1 PLACE ± 0.25 ± ---		0 PLACE ± --- ± ---		ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 3 OF 3			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											